

ABSTRACT

A semiconductor structure and a method for forming the semiconductor structure, including a semiconductor chip and a conductive layer disposed over a portion of the chip, the conductive layer having a portion that extends beyond an edge of the chip. The chip
5 includes a device, which can be an integrated circuit or a micro-mechanical device. The structure can also include a front layer extending beyond the edge of the chip, the conductive layer being disposed on the front layer.

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